

## 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

#### PCN#20150122000

# LMX9838 Datasheet Changes including Product MIC Certification – Device Symbolization to include MIC Certification Information Only

**Date:** 1/23/2015

To: Newark/Farnell PCN

#### Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this PCN are for your information only. Please see the attachment details for the planned implementation date.

This notification period is per TI's standard process. Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (<u>PCN\_ww\_admin\_team@list.ti.com</u>).

Sincerely,

PCN Team SC Business Services

#### 20150122000 Attachment: 1

## **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

**DEVICE** LMX9838SB/NOPB **CUSTOMER PART NUMBER** 

null

Technical details of this Product Change follow on the next page(s).

PCN Number:			20150122000						PCN Date:	01/23/2015	
Title:			LMX9838 Datasheet Changes including Product MIC Certification – Device								
		Symbolizatio	ion to include MIC Certification								
<b>Customer Contact:</b>			PCN Manager			Dept:	Quality Services				
Change Type:											
	Assembly Site				Assembly Process				Assembly Materials		
Design			$\boxtimes$	Datasheet				Mechanical Sp	ecification		
Test Site			$\boxtimes$	Packing/Shipping/Labeling				Test Process			
Wafer Bump Site					Wafer Bump Material				Wafer Bump Process		
Wafer Fab Site				Wafer Fab Materials				Wafer Fab Process			
					Part number change						

# **PCN Details**

## **Description of Change:**

The LMX9838 datasheet will undergo updates including a change to reflect the recently obtained MIC Certification. Sections 8.3.4 and 11 have been updated to reflect this certification. Top-side Symbolization will accordingly be changed to reflect this MIC Certification Marking as shown below. No changes in testing, materials or manufacturing sites are associated with this MIC certification.



#### Datasheet Changes:

#### 5 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

#### Changes from Revision E (January 2014) to Revision F

Page

- Added Handling Rating table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section

The datasheet number will be changing:

Device Family	Change From:	Change To:
LMX9838	SNOSAZ9E	SNOSAZ9F

These changes may be reviewed at the datasheet links provided.

The updated datasheet can be accessed by the following link:

http://www.ti.com/product/lmx9838?keyMatch=lmx9838&tisearch=Search-EN

#### **Reason for Change:**

To reflect recently obtained MIC certification.

# Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:							
Device symbolization with MIC mark							
Product Affected:							
LMX9838SB/NOPB	LMX9838SBX/NOPB						

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com